

SKM100GB12T4



SEMITRANS®2

Fast IGBT4 Modules

SKM100GB12T4

Features

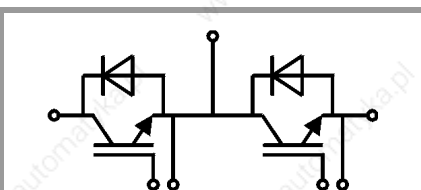
- IGBT4 = 4. Generation (Trench)IGBT
- VCEsat with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_{CNOM}$
- Soft switching 4. Generation CAL diode (CAL4)

Typical Applications

- AC inverter drives
- UPS
- Electronic welders at fsw up to 20 kHz

Remarks

- Case temperature limited to $T_c = 125^\circ\text{C}$ max, recomm. $T_{op} = -40 \dots +150^\circ\text{C}$, product rel. results valid for $T_j = 150^\circ$



GB

Absolute Maximum Ratings				
Symbol	Conditions	Values	Unit	
IGBT				
V_{CES}		1200	V	
I_C	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	160	A
		$T_c = 80^\circ\text{C}$	123	A
I_{Cnom}		100	A	
I_{CRM}	$I_{CRM} = 3 \times I_{Cnom}$	300	A	
V_{GES}		-20 ... 20	V	
t_{psc}	$V_{CC} = 800\text{ V}$	$T_j = 150^\circ\text{C}$	10	μs
	$V_{GE} \leq 15\text{ V}$			
	$V_{CES} \leq 1200\text{ V}$			
T_j		-40 ... 175		$^\circ\text{C}$
Inverse diode				
I_F	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	121	A
		$T_c = 80^\circ\text{C}$	91	A
I_{Fnom}		100	A	
I_{FRM}	$I_{FRM} = 3 \times I_{Fnom}$	300	A	
I_{FSM}	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$	550	A	
T_j		-40 ... 175		$^\circ\text{C}$
Module				
$I_{t(RMS)}$		200		A
T_{stg}		-40 ... 125		$^\circ\text{C}$
V_{isol}	AC sinus 50Hz, $t = 1\text{ min}$	4000		V

Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
IGBT					
$V_{CE(sat)}$	$I_C = 100\text{ A}$ $V_{GE} = 15\text{ V}$ chiplevel	$T_j = 25^\circ\text{C}$	1.8	2.05	V
		$T_j = 150^\circ\text{C}$	2.2	2.4	V
V_{CE0}		$T_j = 25^\circ\text{C}$	0.8	0.9	V
		$T_j = 150^\circ\text{C}$	0.7	0.8	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	10.0	11.5	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	15.0	16.0	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 3.8\text{ mA}$	5	5.8	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$	0.1	0.3	mA
		$T_j = 150^\circ\text{C}$			mA
C_{ies}	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	6.15		nF
C_{oes}		$f = 1\text{ MHz}$	0.40		nF
C_{res}		$f = 1\text{ MHz}$	0.345		nF
Q_G	$V_{GE} = -8\text{ V} \dots +15\text{ V}$		565		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		7.5		Ω
$t_{d(on)}$	$V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$	165		ns
t_r	$I_C = 100\text{ A}$ $V_{GE} = \pm 15\text{ V}$	$T_j = 150^\circ\text{C}$	47		ns
		$T_j = 150^\circ\text{C}$	15		mJ
E_{on}	$R_{Gon} = 1\ \Omega$	$T_j = 150^\circ\text{C}$			mJ
$t_{d(off)}$	$R_{Goff} = 1\ \Omega$	$T_j = 150^\circ\text{C}$	400		ns
t_f	$di/dt_{on} = 1800\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	75		ns
E_{off}	$di/dt_{off} = 1130\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	10.2		mJ
$R_{th(j-c)}$	per IGBT			0.27	K/W

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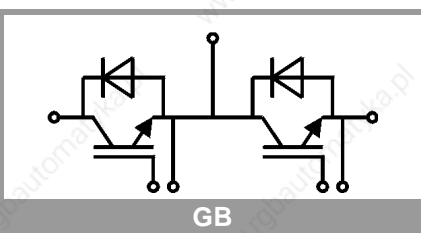
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
$V_F = V_{EC}$	$I_F = 100 \text{ A}$ $V_{GE} = 0 \text{ V}$ chip	$T_j = 25^\circ\text{C}$		2.2	2.52	V
		$T_j = 150^\circ\text{C}$		2.15	2.47	V
V_{F0}		$T_j = 25^\circ\text{C}$		1.3	1.5	V
		$T_j = 150^\circ\text{C}$		0.9	1.1	V
r_F		$T_j = 25^\circ\text{C}$		9.0	10.2	m Ω
		$T_j = 150^\circ\text{C}$		12.5	13.7	m Ω
I_{RRM}	$I_F = 100 \text{ A}$	$T_j = 150^\circ\text{C}$		54		A
Q_{rr}	$di/dt_{off} = 1600 \text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		15.7		μC
E_{rr}	$V_{GE} = \pm 15 \text{ V}$ $V_{CC} = 600 \text{ V}$	$T_j = 150^\circ\text{C}$		5.9		mJ
$R_{th(j-c)}$	per diode				0.48	K/W
Module						
L_{CE}					30	nH
$R_{CC'+EE'}$	terminal-chip	$T_c = 25^\circ\text{C}$		0.65		m Ω
		$T_c = 125^\circ\text{C}$		1		m Ω
$R_{th(c-s)}$	per module			0.04	0.05	K/W
M_s	to heat sink M6			3	5	Nm
M_t		to terminals M5		2.5	5	Nm
						Nm
w					160	g



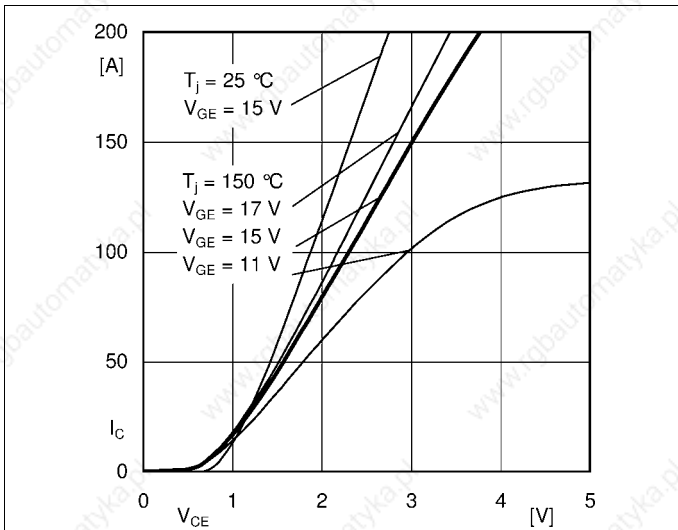


Fig. 1: Typ. output characteristic, inclusive R_{CC}+EE'

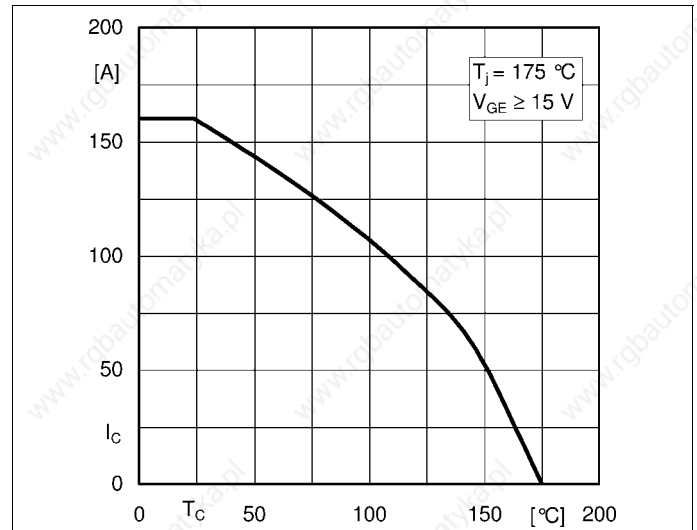


Fig. 2: Rated current vs. temperature I_C = f(T_C)

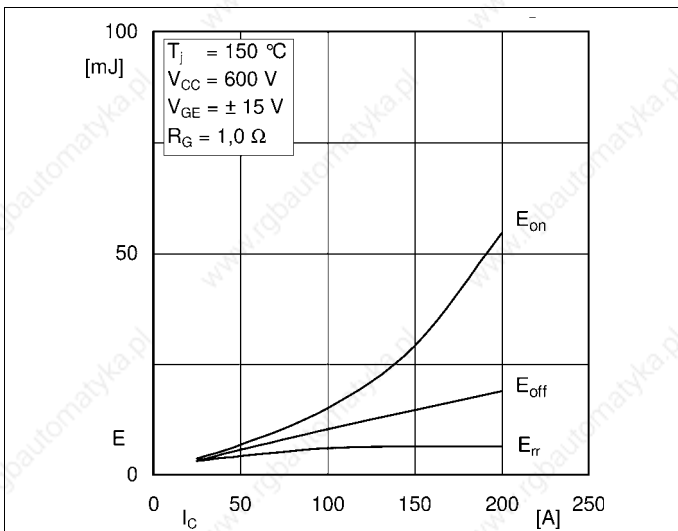


Fig. 3: Typ. turn-on /-off energy = f(I_C)

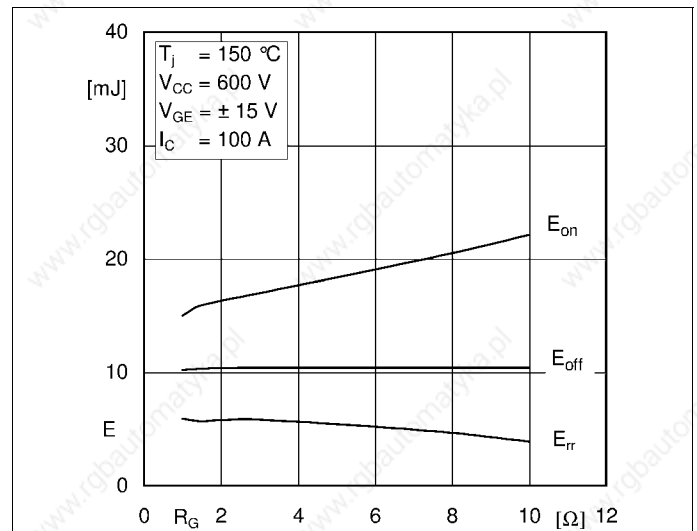


Fig. 4: Typ. turn-on /-off energy = f(R_G)

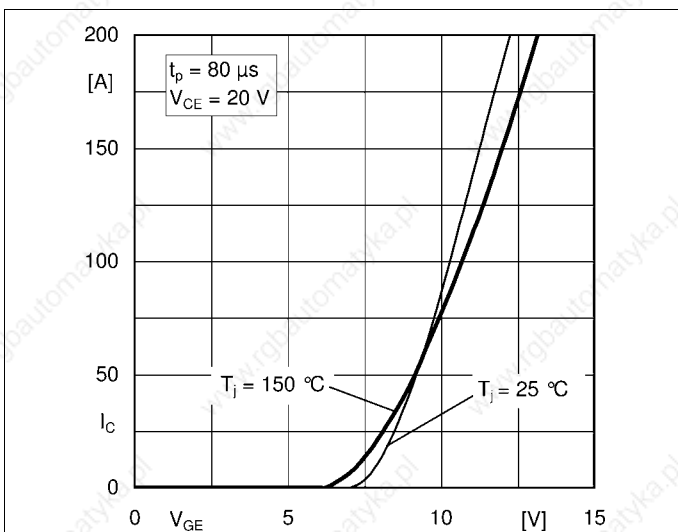


Fig. 5: Typ. transfer characteristic

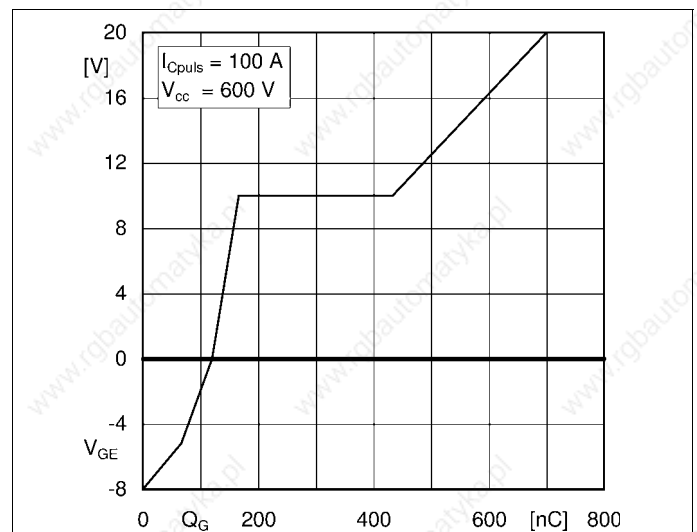
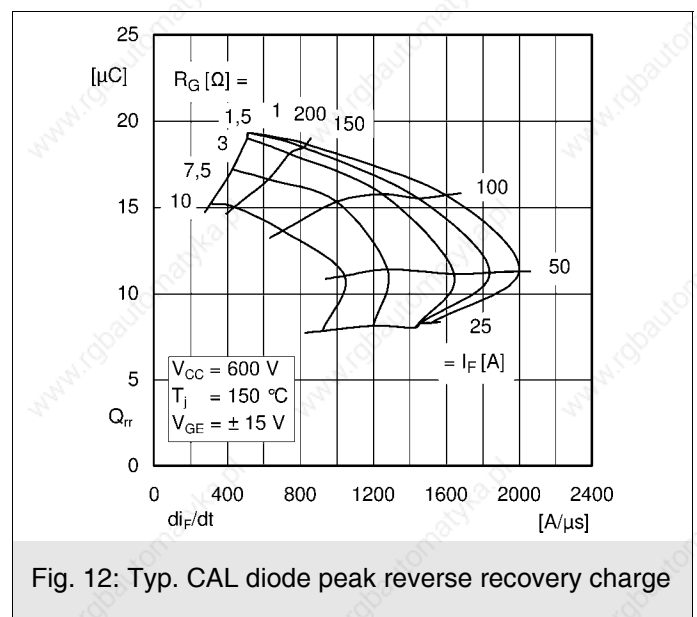
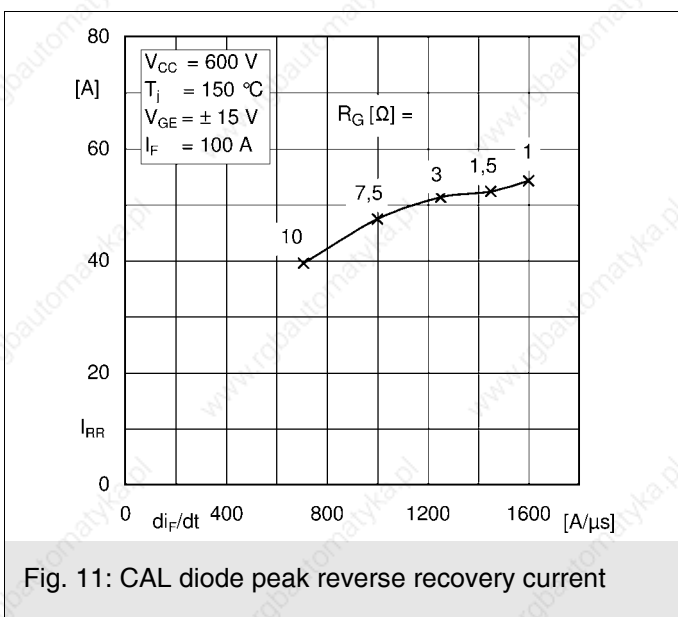
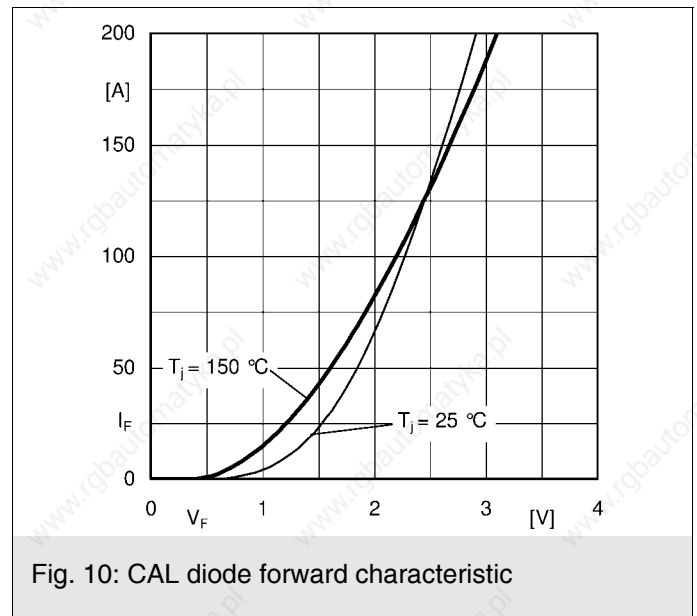
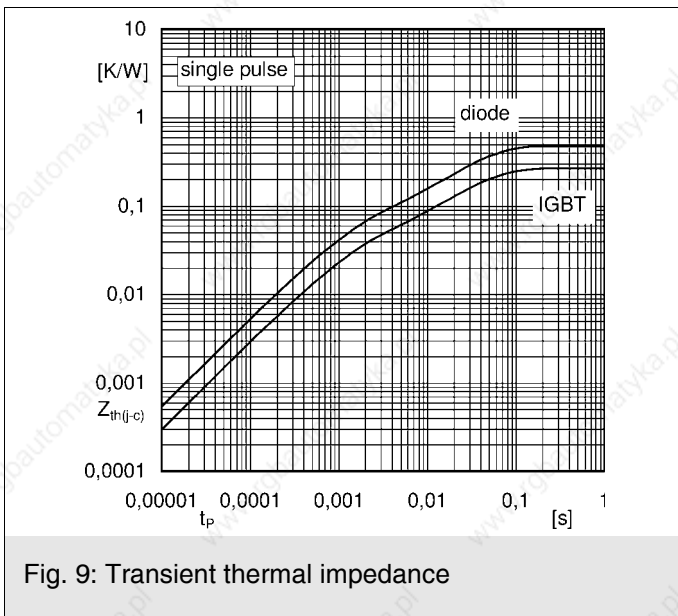
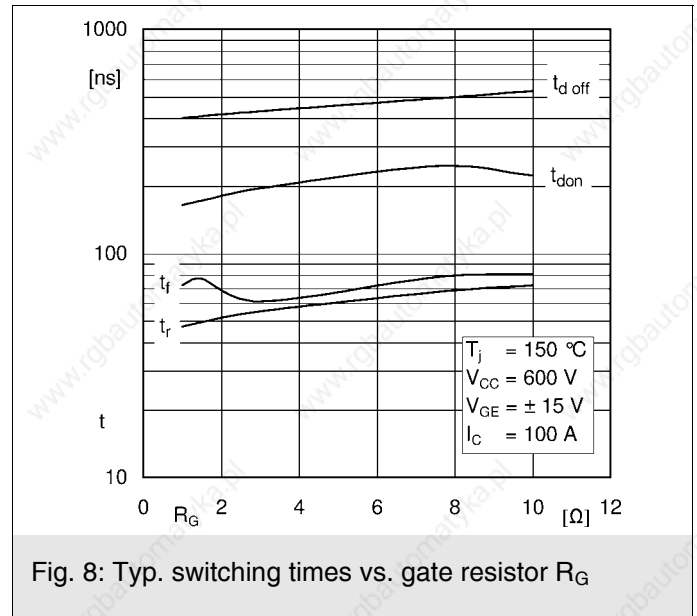
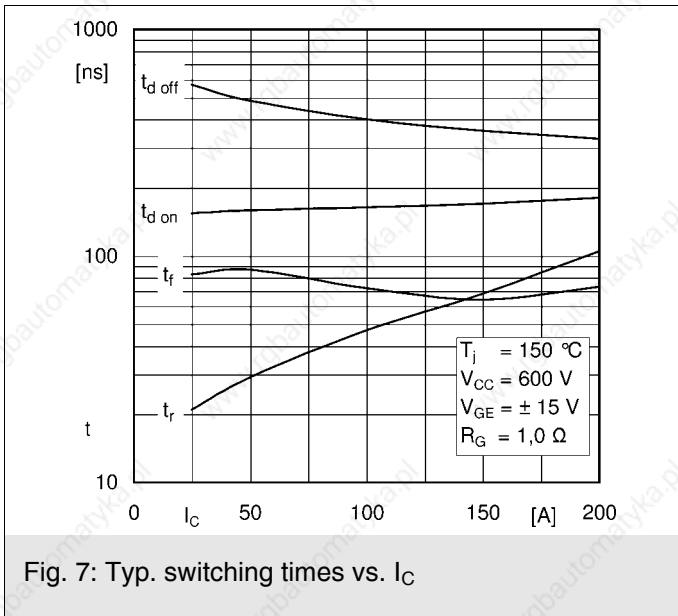
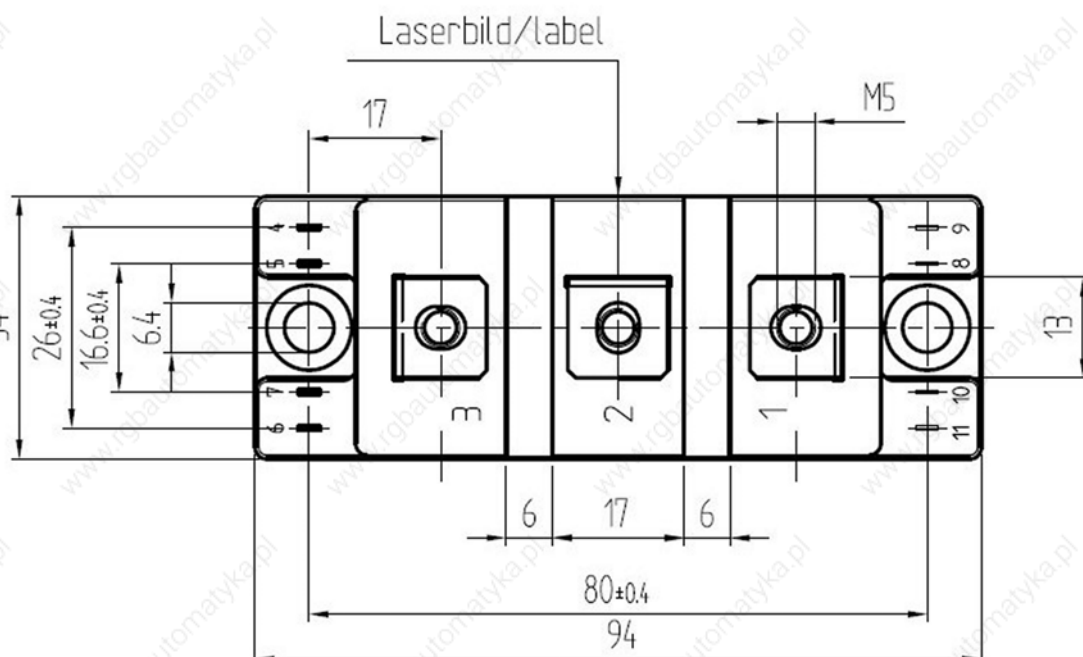
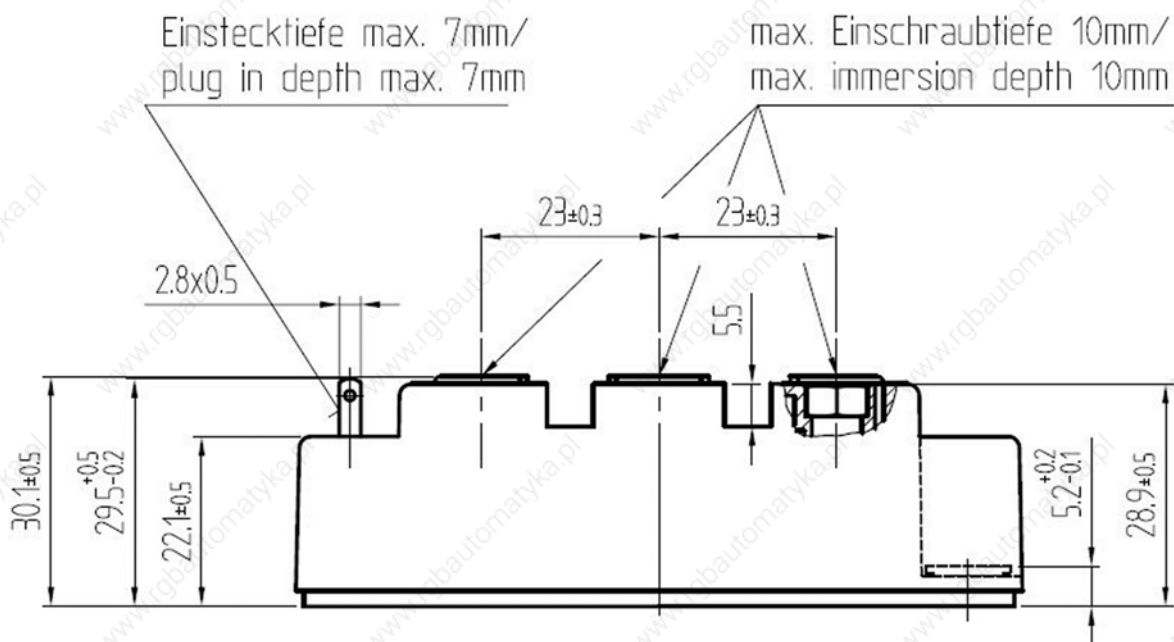


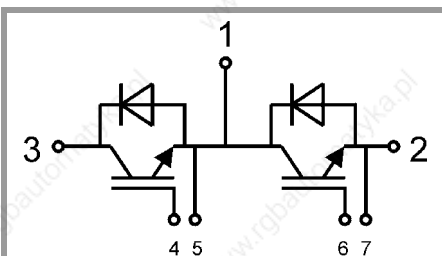
Fig. 6: Typ. gate charge characteristic



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Semitrans 2



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

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